BLÖSCH
high-end coating solutions

Compact solderable coating

FOR DOWN TO SUB-MILLIMETER HIGH-PRECISION HERMETIC PACKAGING

Solderable metal coatings are durable and resist to high temperature and harsh environmental conditions. They provide the highest quality sealing for hermetic packaging.

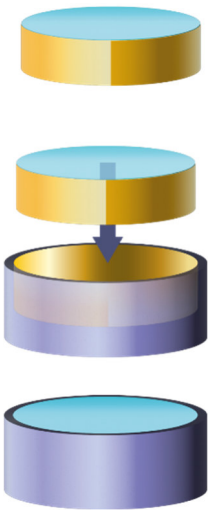
Both Physical Vapor Deposition (PVD) and electroplating belong to Blösch's portfolio of metallization technologies.
Our PVD coating processes are optimized for depositing stacks of metals and alloys.
Our electroplating processes enable the deposition of thick metals layers.
The combination of PVD and electroplating provides unique capability and features for many applications.

Key features

- Solderable coating solutions for the side surface of optical windows or lenses.
- The side surface of very small substrates, down to sub-millimeter dimensions, can be coated for soldering.
- Ideal coating solution for size-critical hermetic windows such as in endoscopes and space-limited sensing devices.
- Cylindrical, flat or other surface shapes can be coated.
- Substrates may be either sapphire, fused silica, or most crystals, glasses and ceramics.
- The windows or lenses can also be anti-reflection coated.

Markets

- Medical & Food
- Sensing
- Aerospace & Defense
- Telecom
- Environmental
- Other applications



Technical data

- Substrates: Sapphire, Fused silica, other crystals and glasses, …
- All forms and shapes, including flat and 3D substrates
- State-of-the-art and proven vacuum deposition and electroplating technologies
- Substrate size from sub-millimeter dimensions up to several tens of millimeters
- Specifications for surface cleanliness and roughness apply
- Solderable layer for either AuSn or AgSn solders
- Adhesive strength > 10 N/mm^2
- Shear strength > 4 N/mm^2
- Sheet resistance < 0.1 Ohm/sq.
- MIL-M-13508C 4.4.6 / 4.4.7

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